

January 2008

74LCX240 Low Voltage Octal Buffer/Line Driver with 5V Tolerant Inputs and Outputs

Features

- 5V tolerant inputs and outputs
- 2.3V–3.6V V_{CC} specifications provided
- 6.5ns t_{PD} max. $(V_{CC} = 3.3V)$, $10\mu A I_{CC}$ max.
- Power-down high impedance inputs and outputs
- Supports live insertion/withdrawal⁽¹⁾
- ± 24 mA output drive ($V_{CC} = 3.0$ V)
- Implements proprietary noise/EMI reduction circuitry
- Latch-up performance exceeds 500mA
- ESD performance:
 - Human body model > 2000V
 - Machine model > 200V

Note:

 To ensure the high-impedance state during power up or down, OE should be tied to V_{CC} through a pull-up resistor: the minimum value or the resistor is determined by the current-sourcing capability of the driver.

General Description

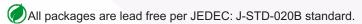
The LCX240 is an inverting octal buffer and line driver designed to be employed as a memory address driver, clock driver and bus oriented transmitter or receiver. The device is designed for low voltage (2.5V or 3.3V) V_{CC} applications with capability of interfacing to a 5V signal environment.

The LCX240 is fabricated with an advanced CMOS technology to achieve high speed operation while maintaining CMOS low power dissipation.

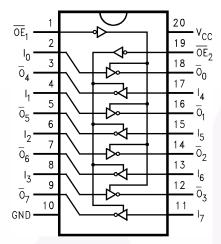
Ordering Information

Order Number	Package Number	Package Description		
74LCX240WM	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide		
74LCX240SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide		
74LCX240MSA	MSA20	20-Lead Shrink Small Outline Package (SSOP), JEDEC MO-150, 5.3mm Wide		
74LCX240MTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide		

Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering number.



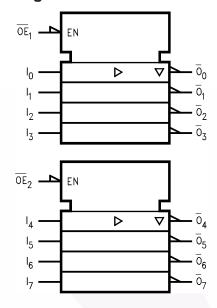
Connection Diagram



Pin Description

Pin Names	Description	
\overline{OE}_1 , \overline{OE}_2	3-STATE Output Enable Inputs	
I ₀ –I ₇	Inputs	
$\overline{O}_0 - \overline{O}_7$	Outputs	

Logic Diagram



Truth Tables

Inp	uts	Outputs
OE ₁	In	(Pins 12, 14, 16, 18)
L	L	Н
L	Н	L
Н	Х	Z

Inp	uts	Outputs
ŌE ₂	In	(Pins 3, 5, 7, 9)
L	L	Н
L	Н	L
Н	Х	Z

H = HIGH Voltage Level

L = LOW Voltage Level

X = Immaterial

Z = High Impedance

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Rating
V _{CC}	Supply Voltage	-0.5V to +7.0V
VI	DC Input Voltage	-0.5V to +7.0V
Vo	DC Output Voltage	
	Output in 3-STATE	-0.5V to +7.0V
	Output in HIGH or LOW State ⁽²⁾	-0.5V to V _{CC} + 0.5V
I _{IK}	DC Input Diode Current, V _I < GND	-50mA
I _{OK}	DC Output Diode Current	
	$V_O < GND$	-50mA
	$V_O > V_{CC}$	+50mA
Io	DC Output Source/Sink Current	±50mA
I _{CC}	DC Supply Current per Supply Pin	±100mA
I _{GND}	DC Ground Current per Ground Pin	±100mA
T _{STG}	Storage Temperature	−65°C to +150°C

Note:

2. IO Absolute Maximum Rating must be observed.

Recommended Operating Conditions⁽³⁾

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Min.	Max.	Units
V _{CC}	Supply Voltage			
	Operating	2.0	3.6	V
	Data Retention	1.5	3.6	
VI	Input Voltage	0	5.5	V
Vo	Output Voltage			
	3-STATE	0	5.5	V
	HIGH or LOW State	0	V _{CC}	
I _{OH} / I _{OL}	Output Current			
	$V_{CC} = 3.0V - 3.6V$		±24	mA
	$V_{CC} = 2.7V - 3.0V$		±12	
	V _{CC} = 2.3V–2.7V		±8	
T _A	T _A Free-Air Operating Temperature		85	°C
Δt / ΔV	Input Edge Rate, V _{IN} = 0.8V–2.0V, V _{CC} = 3.0V	0	10	ns/V

Note

3. Unused inputs must be held HIGH or LOW. They may not float.

DC Electrical Characteristics

				$T_A = -40$ °C	to +85°C	
Symbol	Parameter	V _{CC} (V)	Conditions	Min.	Max.	Units
V _{IH}	HIGH Level Input Voltage	2.3–2.7		1.7		V
		2.7–3.6		2.0		
V _{IL}	LOW Level Input Voltage	2.3–2.7			0.7	V
		2.7–3.6			0.8	
V _{OH}	HIGH Level Output Voltage	2.3–3.6	$I_{OH} = -100 \mu A$	V _{CC} - 0.2		V
		2.3	$I_{OH} = -8mA$	1.8		
		2.7	I _{OH} = -12mA	2.2		
		3.0	I _{OH} = -18mA	2.4		
			$I_{OH} = -24mA$	2.2		
V _{OL}	LOW Level Output Voltage	2.3–3.6	I _{OL} = 100μA		0.2	V
		2.3	I _{OL} = 8mA		0.6	
		2.7	I _{OL} = 12mA		0.4	
		3.0	I _{OL} = 16mA	V	0.4	
			I _{OL} = 24mA		0.55	
I _I	Input Leakage Current	2.3–3.6	$0 \le V_I \le 5.5V$		±5.0	μΑ
I _{OFF}	Power-Off Leakage Current		V_I or $V_O = 5.5V$		10	μA
I _{CC}	Quiescent Supply Current	2.3–3.6	$V_I = V_{CC}$ or GND		10	μΑ
			$3.6V \le V_I, V_O \le 5.5V^{(4)}$		±10	
ΔI_{CC}	Increase in I _{CC} per Input	2.3–3.6	$V_{IH} = V_{CC} = 0.6V$		500	μA

Note:

4. Outputs disabled or 3-STATE only.

AC Electrical Characteristics

		$T_A = -40$ °C to +85°C, $R_L = 500\Omega$						
			3V ± 0.3V, 50pF		2.7V, 50pF	V _{CC} = 2.5 C _L =	V ± 0.2V, 30pF	
Symbol	Parameter	Min.	Max.	Min.	Max.	Min.	Max.	Units
t _{PHL} , t _{PLH}	Propagation Delay	1.5	6.5	1.5	7.5	1.5	7.8	ns
t _{PZL} , t _{PZH}	Output Enable Time	1.5	8.0	1.5	9.0	1.5	10.0	ns
t _{PLZ} , t _{PHZ}	Output Disable Time	1.5	7.0	1.5	8.0	1.5	8.4	ns
t _{OSHL} , t _{OSLH}	Output to Output Skew ⁽⁵⁾		1.0					ns

Note:

 Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}).

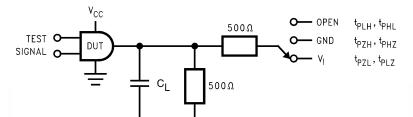
Dynamic Switching Characteristics

				$T_A = 25^{\circ}C$	
Symbol	Parameter	V _{CC} (V)	Conditions	Typical	Unit
V _{OLP}	Quiet Output Dynamic Peak V _{OL}	3.3	$C_L = 50pF, V_{IH} = 3.3V, V_{IL} = 0V$	0.8	V
		2.5	$C_L = 30 pF, V_{IH} = 2.5 V, V_{IL} = 0 V$	0.6	
V _{OLV}	Quiet Output Dynamic Valley V _{OL}	3.3	$C_L = 50 pF, V_{IH} = 3.3 V, V_{IL} = 0 V$	-0.8	V
		2.5	$C_L = 30pF, V_{IH} = 2.5V, V_{IL} = 0V$	-0.6	

Capacitance

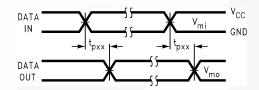
Symbol	Parameter	Conditions	Typical	Units
C _{IN}	Input Capacitance	V_{CC} = Open, V_I = 0V or V_{CC}	7	pF
C _{OUT}	Output Capacitance	$V_{CC} = 3.3V$, $V_I = 0V$ or V_{CC}	8	pF
C _{PD}	Power Dissipation Capacitance	$V_{CC} = 3.3V$, $V_I = 0V$ or V_{CC} , $f = 10MHz$	25	pF

AC Loading and Waveforms (Generic for LCX Family)

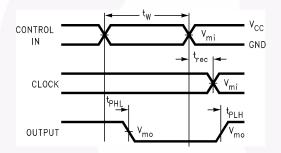


Test	Switch
t _{PLH} , t _{PHL}	Open
t_{PZL}, t_{PLZ}	6V at $V_{CC} = 3.3 \pm 0.3V$ $V_{CC} \times 2$ at $V_{CC} = 2.5 \pm 0.2V$
t _{PZH} , t _{PHZ}	GND

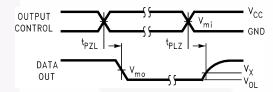
Figure 1. AC Test Circuit (C_L includes probe and jig capacitance)



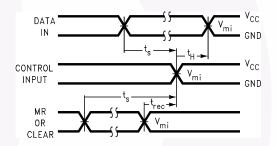
Waveform for Inverting and Non-Inverting Functions



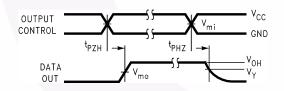
Propagation Delay. Pulse Width and t_{rec} Waveforms



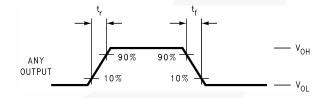
3-STATE Output High Enable and Disable Times for Logic



Setup Time, Hold Time and Recovery Time for Logic



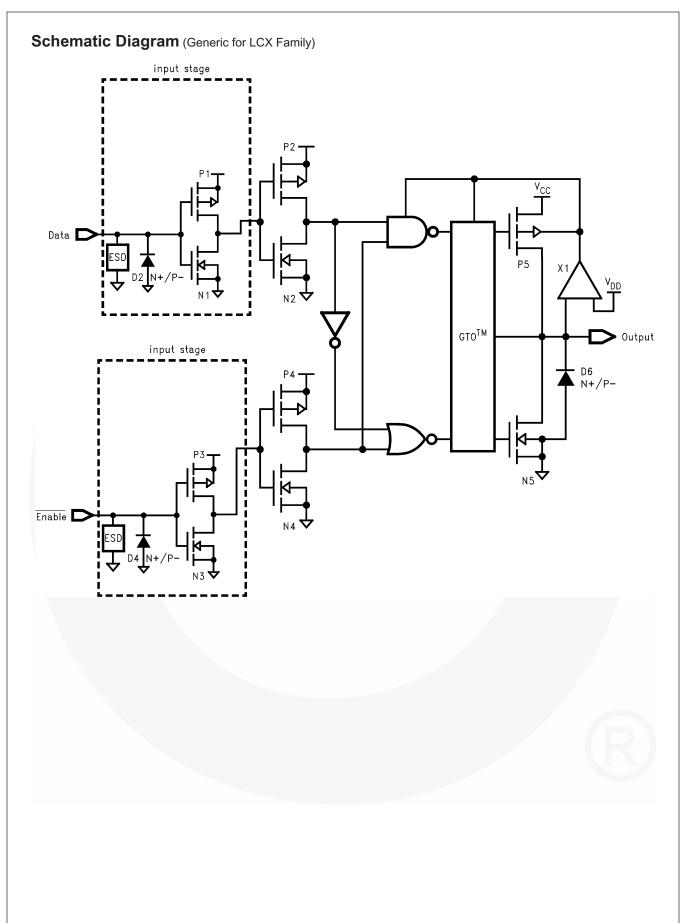




t_{rise} and t_{fall}

ſ		V _{cc}				
	Symbol	3.3V ± 0.3V	2.7V	2.5V ± 0.2V		
	V_{mi}	1.5V	1.5V	V _{CC} /2		
	V _{mo}	1.5V	1.5V	V _{CC} /2		
Г	V _x	V _{OL} + 0.3V	V _{OL} + 0.3V	V _{OL} + 0.15V		
	V _y	V _{OH} – 0.3V	V _{OH} – 0.3V	V _{OH} – 0.15V		

Figure 2. Waveforms (Input Characteristics; f = 1MHz, $t_r = t_f = 3ns$)



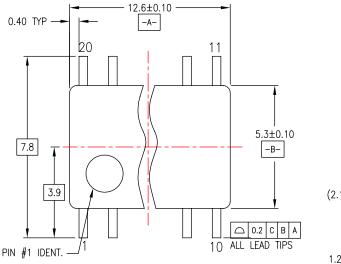
Physical Dimensions 13.00 12.60 11.43 В 9.50 10.65 7.60 10.00 7.40 PIN ONE 0.35 INDICATOR **⊕** 0.25 **M** C B A LAND PATTERN RECOMMENDATION 2.65 MAX SEE DETAIL A 0.33 0.20 △ 0.10 C 0.30 0.10 0.75 SEATING PLANE NOTES: UNLESS OTHERWISE SPECIFIED (R0.10) A) THIS PACKAGE CONFORMS TO JEDEC GAGE PLANE MS-013, VARIATION AC, ISSUE E (R0.10) B) ALL DIMENSIONS ARE IN MILLIMETERS. 0.25 C) DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS. D) CONFORMS TO ASME Y14.5M-1994 0.40 SEATING PLANE E) LANDPATTERN STANDARD: SOIC127P1030X265-20L (1.40)DETAIL A F) DRAWING FILENAME: MKT-M20BREV3

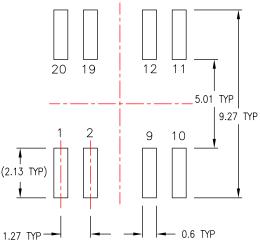
Figure 3. 20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide

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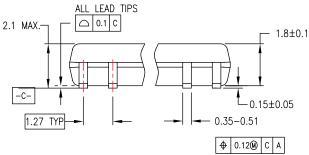
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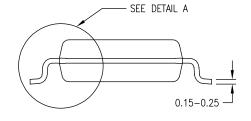
Physical Dimensions (Continued)





LAND PATTERN RECOMMENDATION



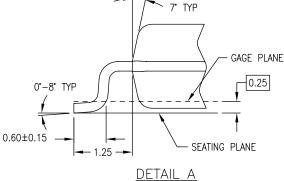


DIMENSIONS ARE IN MILLIMETERS

NOTES:

- A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.

 B. DIMENSIONS ARE IN MILLIMETERS.
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M20DREVC

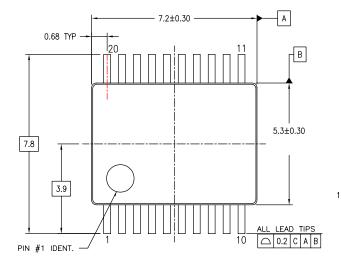
Figure 4. 20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide

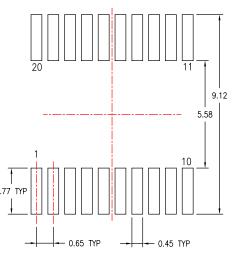
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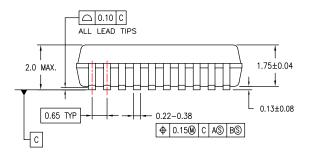
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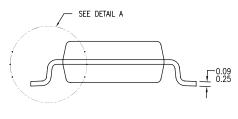
Physical Dimensions (Continued)





LAND PATTERN RECOMMENDATIONS

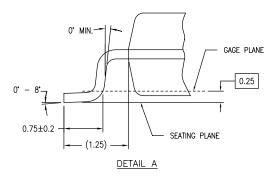




DIMENSIONS ARE IN MILLIMETERS

NOTES:

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- D. DIMENSIONS AND TOLERANCES PER ASME Y14.5M 1994.



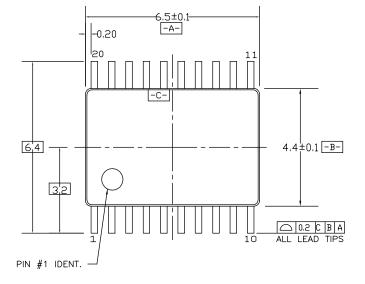
MSA20REVB

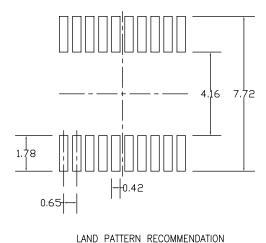
Figure 5. 20-Lead Shrink Small Outline Package (SSOP), JEDEC MO-150, 5.3mm Wide

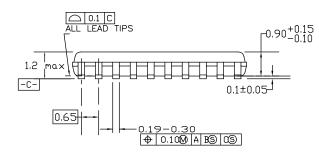
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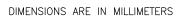
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Physical Dimensions (Continued)



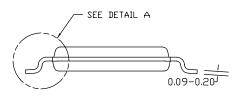


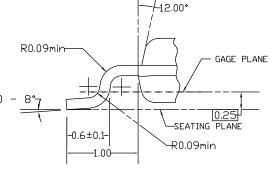




NOTES:

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- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLDS FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.





DETAIL A

MTC20REVD1

Figure 6. 20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

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